
Identification cards — Test methods —
Part 3:
Integrated circuit cards with contacts and
related interface devices

Cartes d'identification — Méthodes d'essai —

*Partie 3: Cartes à circuit(s) intégré(s) à contacts et dispositifs d'interface
assimilés*

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Contents

Page

| | |
|--|-----------|
| Foreword | v |
| 1 Scope | 1 |
| 2 Normative references | 1 |
| 3 Terms and definitions | 2 |
| 4 General items applicable to the test methods | 2 |
| 4.1 Test environment | 2 |
| 4.2 Pre-conditioning | 2 |
| 4.3 Selection of test methods | 3 |
| 4.4 Default tolerance | 3 |
| 4.5 Total measurement uncertainty | 3 |
| 4.6 Conventions for electrical measurements | 3 |
| 4.7 Apparatus | 3 |
| 4.7.1 Apparatus for testing the integrated circuit cards with contacts (card-test-apparatus) | 3 |
| 4.7.2 Apparatus for testing the interface device (IFD-test-apparatus) | 8 |
| 4.7.3 Test Scenario | 13 |
| 4.8 Relationship of test methods versus base standard requirements | 13 |
| 5 Test methods for electrical characteristics of cards with contacts | 16 |
| 5.1 VCC contact | 16 |
| 5.1.1 Apparatus | 16 |
| 5.1.2 Procedure | 16 |
| 5.1.3 Test report | 17 |
| 5.2 I/O contact | 17 |
| 5.2.1 Apparatus | 17 |
| 5.2.2 Procedure | 17 |
| 5.2.3 Test report | 19 |
| 5.3 CLK contact | 19 |
| 5.3.1 Apparatus | 19 |
| 5.3.2 Procedure | 19 |
| 5.3.3 Test report | 20 |
| 5.4 RST contact | 20 |
| 5.4.1 Apparatus | 20 |
| 5.4.2 Procedure | 20 |
| 5.4.3 Test report | 21 |
| 5.5 SPU (C6) contact | 21 |
| 6 Test methods for logical operations of cards with contacts | 21 |
| 6.1 Answer to Reset (ATR) | 21 |
| 6.1.1 Cold Reset and Answer-to-Reset (ATR) | 21 |
| 6.1.2 Warm Reset | 22 |
| 6.2 T=0 Protocol | 22 |
| 6.2.1 I/O transmission timing for T=0 protocol | 22 |
| 6.2.2 I/O character repetition for T=0 protocol | 23 |
| 6.2.3 I/O reception timing and error signaling for T=0 protocol | 24 |
| 6.3 T=1 Protocol | 25 |
| 6.3.1 I/O transmission timing for T=1 protocol | 25 |
| 6.3.2 I/O reception timing for T=1 protocol | 25 |
| 6.3.3 Character Waiting Time (CWT) behavior | 26 |
| 6.3.4 card-reaction to IFD exceeding character waiting time (CWT) | 27 |
| 6.3.5 Block Guard time (BGT) | 27 |
| 6.3.6 Block sequencing by the card | 28 |

| | | |
|--------|---|----|
| 6.3.7 | Reaction of the card to protocol errors | 31 |
| 6.3.8 | Recovery of a transmission error by the card | 31 |
| 6.3.9 | Resynchronization | 32 |
| 6.3.10 | IFSD negotiation | 33 |
| 6.3.11 | Abortion by the IFD | 34 |
| 7 | Test methods for physical and electrical characteristics of the IFD | 35 |
| 7.1 | Activation of contacts | 35 |
| 7.1.1 | Apparatus | 35 |
| 7.1.2 | Procedure | 35 |
| 7.1.3 | Test report | 35 |
| 7.2 | VCC contact | 36 |
| 7.2.1 | Apparatus | 36 |
| 7.2.2 | Procedure | 36 |
| 7.2.3 | Test report | 37 |
| 7.3 | I/O contact | 37 |
| 7.3.1 | Apparatus | 37 |
| 7.3.2 | Procedure | 37 |
| 7.3.3 | Test report | 39 |
| 7.4 | CLK contact | 39 |
| 7.4.1 | Apparatus | 39 |
| 7.4.2 | Procedure | 39 |
| 7.4.3 | Test report | 41 |
| 7.5 | RST contact | 41 |
| 7.5.1 | Apparatus | 41 |
| 7.5.2 | Procedure | 41 |
| 7.5.3 | Test report | 42 |
| 7.6 | SPU (C6) contact | 42 |
| 7.7 | Deactivation of the contacts | 42 |
| 7.7.1 | Apparatus | 42 |
| 7.7.2 | Procedure | 42 |
| 7.7.3 | Test report | 43 |
| 8 | Test methods for logical operations of the IFD | 43 |
| 8.1 | Answer to Reset (ATR) | 43 |
| 8.1.1 | Card Reset (cold reset) | 43 |
| 8.1.2 | card Reset (warm reset) | 43 |
| 8.2 | T=0 Protocol | 44 |
| 8.2.1 | I/O transmission timing for T=0 protocol | 44 |
| 8.2.2 | I/O character repetition for T=0 protocol | 44 |
| 8.2.3 | I/O reception timing and error signaling for T=0 protocol | 45 |
| 8.3 | T=1 Protocol | 46 |
| 8.3.1 | I/O transmission timing for T=1 protocol | 46 |
| 8.3.2 | I/O reception timing for T=1 protocol | 47 |
| 8.3.3 | IFD Character Waiting Time (CWT) behavior | 48 |
| 8.3.4 | IFD-reaction to card exceeding CWT | 49 |
| 8.3.5 | Block Guard time (BGT) | 49 |
| 8.3.6 | Block sequencing by the IFD | 50 |
| 8.3.7 | Recovery of a transmission error by the IFD | 52 |
| 8.3.8 | IFSC negotiation | 53 |
| 8.3.9 | Abortion by the card | 53 |
| 8.4 | IFD — Reaction of the IFD to invalid PCBs | 54 |
| 8.4.1 | Apparatus | 54 |
| 8.4.2 | Procedure | 54 |
| 8.4.3 | Test report | 55 |

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Foreword

ISO (the International Organization for Standardization) and IEC (the International Electrotechnical Commission) form the specialized system for worldwide standardization. National bodies that are members of ISO or IEC participate in the development of International Standards through technical committees established by the respective organization to deal with particular fields of technical activity. ISO and IEC technical committees collaborate in fields of mutual interest. Other international organizations, governmental and non-governmental, in liaison with ISO and IEC, also take part in the work. In the field of information technology, ISO and IEC have established a joint technical committee, ISO/IEC JTC 1.

International Standards are drafted in accordance with the rules given in the ISO/IEC Directives, Part 2.

The main task of the joint technical committee is to prepare International Standards. Draft International Standards adopted by the joint technical committee are circulated to national bodies for voting. Publication as an International Standard requires approval by at least 75 % of the national bodies casting a vote.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. ISO and IEC shall not be held responsible for identifying any or all such patent rights.

ISO/IEC 10373-3 was prepared by Joint Technical Committee ISO/IEC JTC 1, *Information technology*, Subcommittee SC 17, *Cards and personal identification*.

This second edition cancels and replaces the first edition (ISO/IEC 10373-3:2001), which has been technically revised.

ISO/IEC 10373 consists of the following parts, under the general title *Identification cards — Test methods*:

- *Part 1: General characteristics*
- *Part 2: Cards with magnetic stripes*
- *Part 3: Integrated circuit cards with contacts and related interface devices*
- *Part 5: Optical memory cards*
- *Part 6: Proximity cards*
- *Part 7: Vicinity cards*
- *Part 8: USB-ICC*

The following part is under preparation:

- *Part 9: Optical memory cards: Holographic recording method*

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Identification cards — Test methods —

Part 3:

Integrated circuit cards with contacts and related interface devices

1 Scope

This part of ISO/IEC 10373 defines test methods for characteristics of integrated circuit cards with contacts and related interface devices according to the definition given in ISO/IEC 7816. Each test method is cross-referenced to one or more base standards, which can be ISO/IEC 7810 or one or more of the supplementary International Standards that define the information storage technologies employed in identification card applications.

NOTE Criteria for acceptability do not form part of this part of ISO/IEC 10373 but will be found in the International Standards mentioned above.

This part of ISO/IEC 10373 defines test methods which are specific to integrated circuit technology with contacts. ISO/IEC 10373-1 defines test methods which are common to one or more card technologies and other parts define other technology-specific tests.

Test methods defined in this part of ISO/IEC 10373 are intended to be performed separately and independently. A given card is not required to pass through all the tests sequentially. The test methods defined in this part of ISO/IEC 10373 are based on ISO/IEC 7816-3.

Conformance of cards and IFDs determined using the test methods defined in this part of ISO/IEC 10373 does not preclude failures in the field. Reliability testing is outside the scope of this part of ISO/IEC 10373.

This part of ISO/IEC 10373 does not define any test to establish the complete functioning of integrated circuit cards. The test methods require only that the minimum functionality be verified. Minimum functionality is defined as follows.

- Any integrated circuit present in the card continues to show an Answer to Reset response which conforms to the base standard.
- Any contacts associated with any integrated circuit present in the card continue to show electrical resistance which conforms to the base standard.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

ISO/IEC 7810:2003, *Identification cards — Physical characteristics*

ISO/IEC 7816-3:2006, *Identification cards — Integrated circuit cards — Part 3: Cards with contacts — Electrical interface and transmission protocols*

ISO/IEC 7816-4:2005, *Identification cards — Integrated circuit cards — Part 4: Organization, security and commands for interchange*

3 Terms and definitions

For the purposes of this document, the following terms and definitions apply.

3.1

card

integrated circuit card with contacts as defined in ISO/IEC 7816

3.2

DUT

device under test

card or IFD that is subject to testing

3.3

etu-factor

parameters negotiable by protocol and parameters selection (PPS), described in ISO/IEC 7816-3:2006, 6.3.1

3.4

IFD

interface device related to integrated circuit cards with contacts as defined in ISO/IEC 7816-3

3.5

normal use

use as an identification card, as defined in ISO/IEC 7810:2003, 4.1, involving equipment processes appropriate to the card technology and storage as a personal document between equipment processes

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3.6

test method

method for testing characteristics of identification cards and related interface devices for the purpose of confirming their compliance with International Standards

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3.7

test scenario

defined typical protocol and application specific communication to be used with the test methods defined in this part of ISO/IEC 10373

3.8

typical protocol and application specific communication

communication between a DUT and the corresponding test-apparatus based on protocol and application implemented in the DUT and representing its normal use

4 General items applicable to the test methods

4.1 Test environment

Unless otherwise specified, testing of physical, electrical and logical characteristics shall take place in an environment of temperature $23\text{ °C} \pm 3\text{ °C}$, of relative humidity 40 % to 60 %.

4.2 Pre-conditioning

Where pre-conditioning is required by the test method, the identification cards to be tested shall be conditioned to the test environment for a period of 24 h before testing unless otherwise specified.

4.3 Selection of test methods

Tests shall be applied as required to test the attributes of the card defined by the relevant base standard (see 4.8).

4.4 Default tolerance

Unless otherwise specified, a default tolerance of $\pm 5\%$ shall be applied to the quantity values given to specify the characteristics of the test equipment (e.g. linear dimensions) and the test method procedures (e.g. test equipment adjustments).

4.5 Total measurement uncertainty

The total measurement uncertainty for each quantity determined by these test methods shall be stated in the test report.

4.6 Conventions for electrical measurements

Potential differences are defined with respect to the GND contact of the card and currents flowing to the card are considered positive.

4.7 Apparatus

4.7.1 Apparatus for testing the integrated circuit cards with contacts (card-test-apparatus)

4.7.1.1 Generating the VCC voltage (U_{CC}) and timing

Table 1 — voltage and timing for VCC

| Parameter | Operating Condition | Range | Accuracy |
|------------|---------------------|--------------------------|-------------------|
| U_{CC} | Class A, B, C | -1 V to 6 V | ± 20 mV |
| t_R, t_F | Class A, B, C | 0 μ s to 500 μ s | ± 100 μ s |

4.7.1.2 Measuring ICC

Table 2 — I_{CC} parameters

| Characteristic | Mode | Range | Accuracy | Resolution |
|----------------|-------------------|--------------------------|------------------|--------------------|
| I_{CC} | Spike Measurement | 0 mA to 200 mA | ± 2 mA | 20 ns |
| | Active mode | 0 mA to 100 mA | ± 1 mA | Averaged over 1 ms |
| | Clock stop | 0 μ A to 200 μ A | ± 10 μ A | Averaged over 1 ms |

4.7.1.3 Generating SPU (C6) voltage

See 5.5 and ISO/IEC 7816-3.

4.7.1.4 Generating the RST voltage and timing

Table 3 — RST voltage and timing

| Parameter | Operating Condition | Range | Accuracy |
|---|---------------------|------------------------|-------------|
| U_{IH}, U_{IL} | Class A, B | -1 V to 6 V | ± 20 mV |
| U_{IH} | Class C | -1 V to 2 V | ± 20 mV |
| U_{IL} | Class C | -1 V to 1 V | ± 20 mV |
| t_R, t_F | | 0 μ s to 2 μ s | ± 20 ns |
| NOTE t_R and t_F are generated between 10% and 90% of V_H min and V_L max values. | | | |

4.7.1.5 Measuring the RST current

Table 4 — RST current

| Characteristic | Mode | Range | Accuracy | Resolution |
|----------------|--------|----------------------------|------------------|------------|
| I_{IH} | Active | -30 μ A to 200 μ A | ± 10 μ A | 100 ns |
| I_{IL} | Active | 200 μ A to 30 μ A | ± 10 μ A | 100 ns |

ISO/IEC 10373-3:2010

4.7.1.6 Generating the I/O voltage and timing in reception mode

Table 5 — I/O voltage and timing

| Parameter | Mode | Operating Condition | Range | Accuracy |
|---|--|---------------------|------------------------|--------------|
| U_{IH}, U_{IL} | Card: Reception, Apparatus: Transmission | Class A, B | -1 V to 6 V | ± 20 mV |
| U_{IH} | Card: Reception, Apparatus: Transmission | Class C | -1 V to 2 V | ± 20 mV |
| U_{IL} | Card: Reception, Apparatus: Transmission | Class C | -1 V to 1 V | ± 20 mV |
| t_R, t_F | Card: Reception, Apparatus: Transmission | | 0 μ s to 2 μ s | ± 100 ns |
| NOTE — t_R and t_F are generated between 10% and 90% of V_H min and V_L max values. | | | | |

4.7.1.7 Measuring the I/O current in reception mode

Table 6 — I/O current (reception mode)

| Parameter | Mode | Range | Accuracy | Resolution |
|-----------|--|----------------------------|----------------|------------|
| I_{IH} | Card: Reception, Apparatus: Transmission | -300 μ A to 30 μ A | $\pm 10 \mu$ A | 100 ns |
| I_{IL} | Card: Reception, Apparatus: Transmission | -1,5 mA to -0,2 mA | $\pm 50 \mu$ A | 100 ns |
| | Card: Reception, Apparatus: Transmission | -200 μ A to 30 μ A | $\pm 10 \mu$ A | 100 ns |

4.7.1.8 Generating the I/O current

Table 7 — I/O current

| Parameter | Mode | Range | Accuracy | Stabilization time after level is reached |
|-----------|---|--|------------------|---|
| I_{OH} | Card: Transmission, Apparatus: Reception | 20 k Ω pull-up to VCC or equivalent circuit | $\pm 200 \Omega$ | |
| I_{OL} | Card: Transmission, Apparatus: Reception | 0 mA to 1,5 mA | $\pm 50 \mu$ A | < 100 ns |

4.7.1.9 Measuring the I/O voltage and timing

Table 8 — I/O voltage and timing

| Characteristic | Operating Condition | Range | Accuracy | Resolution |
|------------------|---------------------|------------------------|-------------|------------|
| U_{IH}, U_{IL} | Class A, B, C | -1 V to 6 V | ± 20 mV | 20 ns |
| t_R, t_F | | 0 μ s to 2 μ s | ± 20 ns | |

NOTE — t_R and t_F are measured between 10% and 90% of V_H min and V_L max values.

4.7.1.10 Generating the CLK voltage

Table 9 — CLK voltage

| Parameter | Operating Condition | Range | Accuracy | Resolution |
|------------------|---------------------|-------------|-------------|------------|
| U_{IH}, U_{IL} | Class A, B | -1 V to 6 V | ± 20 mV | 20 ns |
| U_{IH} | Class C | -1 V to 2 V | ± 20 mV | 20 ns |
| U_{IL} | Class C | -1 V to 2 V | ± 20 mV | 20 ns |

4.7.1.11 Generating the CLK waveforms (single cycle measurement)

Table 10 — CLK waveforms

| Parameter | Range | Accuracy |
|------------|------------------------|--------------|
| Duty cycle | 35 % to 65 % of period | ± 5 ns |
| Frequency | 0,5 MHz to 5,5 MHz | ± 5 kHz |
| Frequency | 5 MHz to 20,5 MHz | ± 50 kHz |
| t_R, t_F | 1 % to 10 % of period | ± 5 ns |

NOTE — t_R and t_F are generated between 10% and 90% of V_H (100%) min and V_L (0%) max.

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4.7.1.12 Measuring the CLK current

Table 11 — CLK current

| Characteristic | Mode | Range | Accuracy | Resolution |
|----------------|--------|----------------------------|------------------|------------|
| I_{IH} | active | -30 μ A to 150 μ A | ± 10 μ A | 20 ns |
| I_{IL} | active | -150 μ A to 30 μ A | ± 10 μ A | 20 ns |

4.7.1.13 Measuring the contact capacitance of RST, CLK and I/O

Table 12 — Contact capacitance

| Characteristic | Range | Accuracy |
|----------------|---------------|------------|
| C | 0 pF to 50 pF | ± 5 pF |

The contact capacitance of a contact shall be measured between the contact and the GND contact.

4.7.1.14 Generating the sequence of the activation and deactivation of the contacts

Table 13 — Activation and deactivation

| Range of switching the signals | Accuracy |
|--------------------------------|--|
| 0 s to 1 s | ± 200 ns (or 1 CLK period, whichever is smaller) |

4.7.1.15 Emulating the I/O protocol

The card-test-apparatus shall be able to emulate the protocol T=0 and T=1 and IFD applications which are required to run the typical application specific communications corresponding to the card applications.

NOTE — If a specific functionality is not implemented in the card, the card-test-apparatus is not required to have the corresponding test-capability (e.g. T=1 protocol not implemented in the card).

4.7.1.16 Generating the I/O character timing in reception mode

The card-test-apparatus shall be able to generate the I/O bit stream according to ISO/IEC 7816-3.

All timing parameters like start bit length, guard time, error signaling etc. shall be configurable.

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Table 14 — I/O character timing (reception mode)

| Symbol | Parameter | Accuracy |
|--------------|-----------------------|--------------------|
| ϵ_t | all timing parameters | ± 4 CLK cycles |

4.7.1.17 Measuring and monitoring the I/O protocol

The card-test-apparatus shall be able to measure and monitor the timing of the logical low and high states of the I/O-line relative to the CLK-frequency.

Table 15 — Timing characteristics

| Characteristic | Accuracy |
|----------------------------|--------------------|
| all timing characteristics | ± 2 CLK cycles |

4.7.1.18 Protocol Analysis

The card-test-apparatus shall be able to analyze the I/O-bit stream in accordance to T=0 and T=1 protocol according to ISO/IEC 7816-3 and extract the logical data flow for further protocol and application verifications.

NOTE If a specific functionality is not implemented in the card, the card-test-apparatus is not required to have the corresponding test-capability (e.g. T=1 protocol not implemented in the card). Conversely, an apparatus may need extended capabilities, e.g. being able to generate any case 2 command (see ISO/IEC 7816-4:2005) if a card does not support the standard READ BINARY.

4.7.2 Apparatus for testing the interface device (IFD-test-apparatus)

4.7.2.1 Generating the VCC current (I_{CC})

Table 16 — VCC current

| Parameter | Mode | Range | Accuracy | Stabilization time after level is reached |
|--|-----------------------|----------------------------|-------------------------|---|
| I_{CC} | Spike Generation | 0 mA to 120 mA | ± 2 mA ^b | < 100 ns |
| | Active mode | 0 mA to 70 mA | ± 1 mA | < 100 ns |
| | Idle mode (CLK-Stop) | 0 mA to 1,2 mA | ± 10 μ A | < 100 ns |
| | Inactive ^a | -1,2 mA to 0 mA | ± 10 μ A | < 100 ns |
| t_R, t_F | | 100 ns | ± 50 ns | |
| pulse length | | 100 ns to 500 ns | ± 50 ns | |
| pause length frequently | | 100 ns to 1000 ns | ± 50 ns | |
| pause length randomly | | 10 μ s to 2000 μ s | ± 1 μ s | |
| ^a The maximum output voltage shall be limited to 5 V. ISO/IEC 10373-3:2010 ^b Dynamic conditions for spike generation. https://standards.iteh.ai/catalog/standards/sist/fc1b6b8-85de-48c5-b7aa-4e4a6abe4747/iso-iec-10373-3-2010 | | | | |

4.7.2.2 Measuring the VCC voltage (U_{CC}) and timing

Table 17 — VCC voltage and timing

| Characteristic | Operating Condition | Range | Accuracy | Resolution |
|----------------|---------------------|--------------|-------------|------------|
| U_{CC} | Class A, B, C | - 1 V to 6 V | ± 20 mV | 10 ns |

4.7.2.3 Measuring the SPU (C6) voltage (U_{CC}) and timing

Table 18 — SPU voltage and timing

| Characteristic | Operating Condition | Range | Accuracy | Resolution |
|----------------|---------------------|--------------|-------------|------------|
| U_{CC} | Class A, B, C | - 1 V to 6 V | ± 20 mV | 10 ns |

4.7.2.4 Generating the RST current

Table 19 — RST current

| Parameter | Mode | Range | Accuracy | Stabilization time after level is reached |
|-----------|----------|-----------------------------|------------------|---|
| I_{IH} | active | - 30 μ A to 200 μ A | \pm 10 μ A | < 100 ns |
| I_{IL} | active | - 250 μ A to 30 μ A | \pm 10 μ A | < 100 ns |
| I^a | inactive | - 1,2 mA to 0 mA | \pm 10 μ A | < 100 ns |

^a The output voltage shall be limited from -0,5 V to 5,5 V.

4.7.2.5 Measuring RST voltage and timing

Table 20 — RST voltage and timing

| Characteristic | Operating Condition | Range | Accuracy | Resolution |
|------------------|---------------------|------------------------|-------------|------------|
| U_{IH}, U_{IL} | Class A, B, C | - 1 V to 6 V | \pm 20 mV | 20 ns |
| t_R, t_F | | 0 μ s to 2 μ s | \pm 20 ns | |

NOTE — t_R and t_F are measured between 10% and 90% of V_H min and V_L max values.

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4.7.2.6 Generating the I/O currents

Table 21 — I/O currents

| Parameter | Mode | Range | Accuracy | Stabilization time after level is reached |
|------------------|--|----------------------------|------------------|---|
| I_{IH}, I_{OH} | Apparatus: Reception and Transmission IFD: Transmission and Reception | -400 μ A to 50 μ A | \pm 5 μ A | < 100 ns |
| I_{IL} | Apparatus: Reception IFD: Transmission and Reception | 0 mA to 1,5 mA | \pm 10 μ A | < 100 ns |
| I_{OL} | IFD: Reception | 0 μ A to 1200 μ A | \pm 10 μ A | < 100 ns |
| I^a | Inactive | - 1,2 mA to 0 mA | \pm 10 μ A | < 100 ns |

^a The output voltage shall be limited to -0,5 V to 5,5 V.